Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	2 X 3 X 0.75 (1.65 X 1.8 EP)
Lead Count	8
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	7.97E-03	93.7	937000	57.82	578242
Thermosets	Epoxy Resin	Proprietary	2.55E-04	3.0	30000	1.85	18514
Thermosets	Phenol Resin	Proprietary	2.55E-04	3.0	30000	1.85	18514
Other inorganic materials	Carbon Black	1333-86-4	2.55E-05	0.3	3000	0.19	1851
Subtotal			8.51E-03	100.00	1000000	61.71	617121

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	4.55 E-03	97.50	975000	32.97	329677
Copper & its alloys	Iron	7439-89-6	1.10 E-04	2.35	23500	0.79	7946
Copper & its alloys	Zinc	7440-66-6	5.60 E-06	0.12	1200	0.04	406
Copper & its alloys	Phosphorus	7723-14-0	1.40 E-06	0.03	300	0.01	101
Subtotal			4.66 E-03	100.00	1000000	33.81	338130

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.71 E-05	100.0	1000000	0.34	3416

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	9.00 E-05	100.0	1000000	0.65	6526

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	9.90 E-05	99.00	990000	0.72	7179
Precious metals	Palladium	7440-05-3	1.00 E-06	1.0	10000	0.007	73
Subtotal			1.00 E-04	100.0	1000000	0.73	7252

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.50 E-04	100.0	1000000	2.54	25381

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.42 E-05	80.50	805000	0.18	1751
Other organic materials	Carbocyclic Acrylates	Proprietary	3.00 E-06	10.00	100000	0.02	218
Other organic materials	Bismaleimide resin	Proprietary	9.00 E-07	3.00	30000	0.007	65
Other organic materials	2-preponoic acid, 2-methyl	68586-19-6	9.00 E-07	3.0	30000	0.007	65
Others	Additive	Proprietary	9.00 E-07	3.0	30000	0.007	65
Other organic materials	Dicumyl peroxide	80-43-3	1.50 E-07	0.5	5000	0.001	11
Subtotal			3.00 E-05	100.0	1000000	0.22	2176

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.38 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary